

providing a substrate on a stage, said substrate facing downwardly from a bottom-facing surface of said stage;

positioning a slit coater having a slit nozzle adjacent to and spaced from the substrate a distance corresponding to the desired thickness of said orientation film ; and

C1
Sond spraying an orientation material having a surface tension on the substrate through the slit nozzle of the slit coater while maintaining the surface tension of the orientation material, said orientation material being coated on said stage at a speed which maintains said surface tension.

28. (Amended) A method of forming an orientation film on a substrate comprising:

C2 providing the substrate on a stage, said substrate facing downwardly from a bottom-facing surface of said stage;

positioning a slit coater having a slit nozzle adjacent to and spaced from the substrate a distance corresponding to the desired thickness of said orientation film;

spraying an orientation material having a surface tension on the substrate through the slit nozzle of the slit coater while maintaining the surface tension of the orientation material, said orientation material being coated on said stage at a speed which maintains said surface tension; and

material.
C2

35. (Amended) A method of forming an orientation film on a substrate,
comprising:

providing the substrate on a stage, said substrate facing downwardly from a
bottom-facing surface of said stage;

positioning a slit coater having a slit nozzle and an orientation material, the slit
nozzle being at a predetermined distance from the substrate, and
C3

spraying the orientation material having a surface tension on the substrate through
the slit nozzle of the slit coater while maintaining the surface tension of the orientation
material, said orientation material being coated on said stage at a speed which maintains
said surface tension.

REMARKS

Claims 21-38 remain pending after amendment.